2SD602(A)

Rev.F Apr.-2017

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

SOT-23 NPN Silicon NPN transistor in a SOT-23 Plastic Package.

/ Features

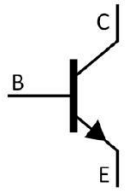
2SB710(A)

Complementary pair with 2SB710(A)Ä

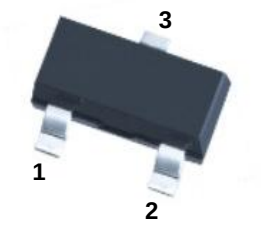
/ Applications

General power amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Emitter PIN 3 Collector

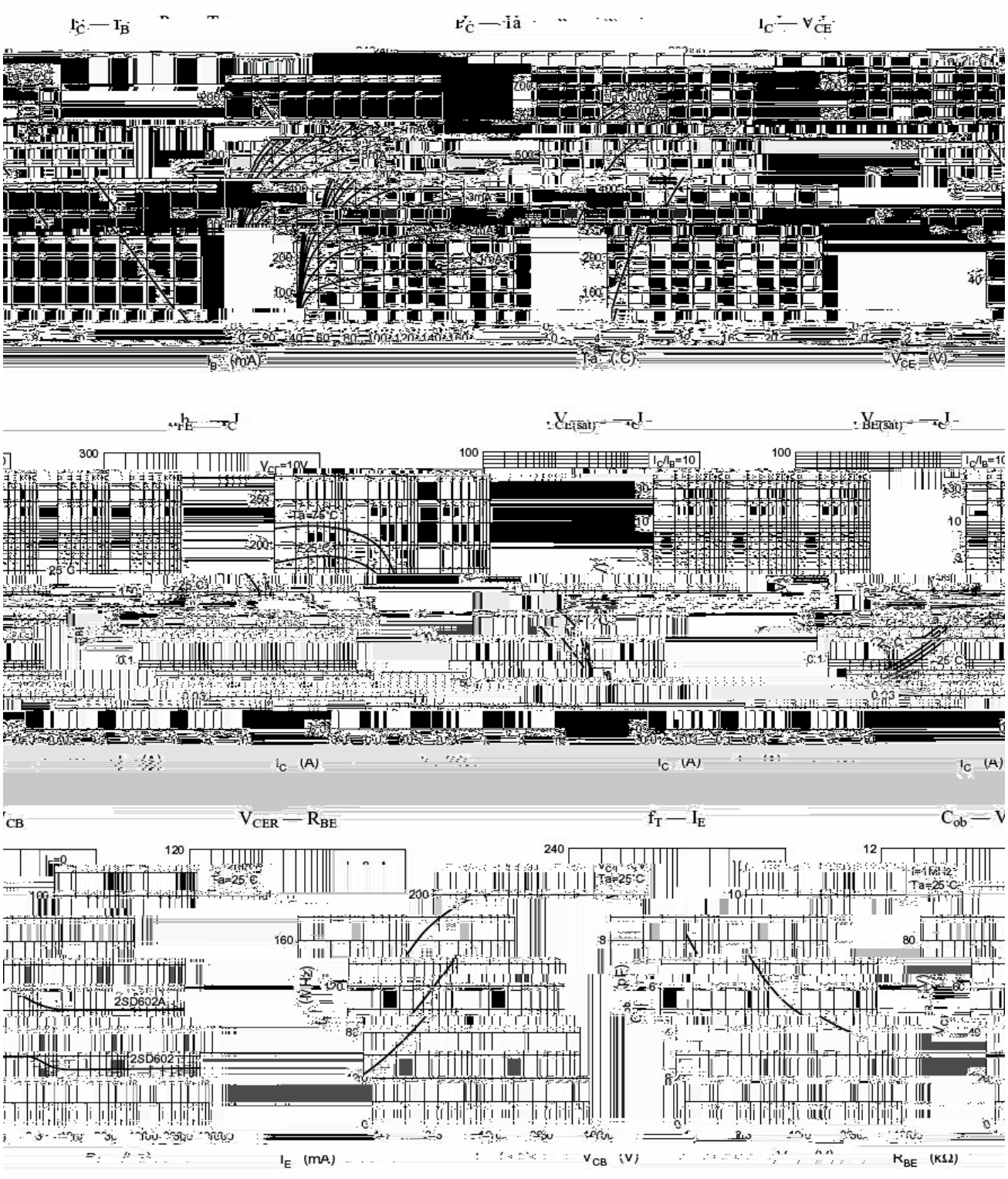
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol		Q	R	S
h_{FE} Range		85-170	120-240	170-340
Marking	2SD602 2SD602A	H2WQ H2XQ	H2WR H2XR	H2WS H2XS

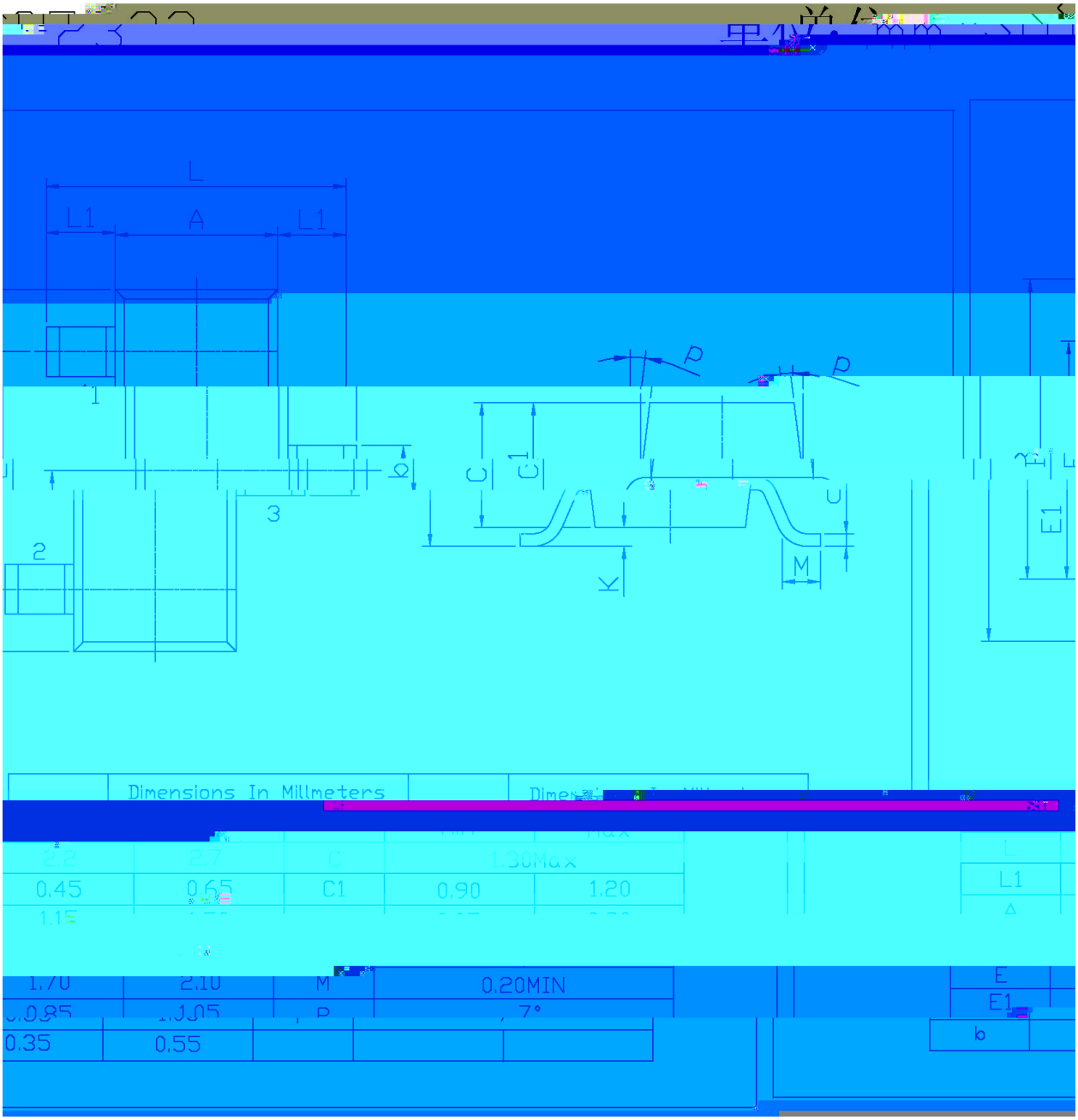
Parameter		Symbol	Rating	Unit
Collector to Base Voltage	2SD602 2SD602A	V_{CBO}	30 60	V
Collector to Emitter Voltage	2SD602 2SD602A	V_{CEO}	25 50	V
Emitter to Base Voltage		V_{EBO}	5.0	V
Collector Current		I_C	500	mA
Collector Current(pulse)		I_{CP}	1.0	A
Collector Power Dissipation		P_C	200	mW
Junction Temperature		T_j	150	
Storage Temperature Range		T_{stg}	-55 150	

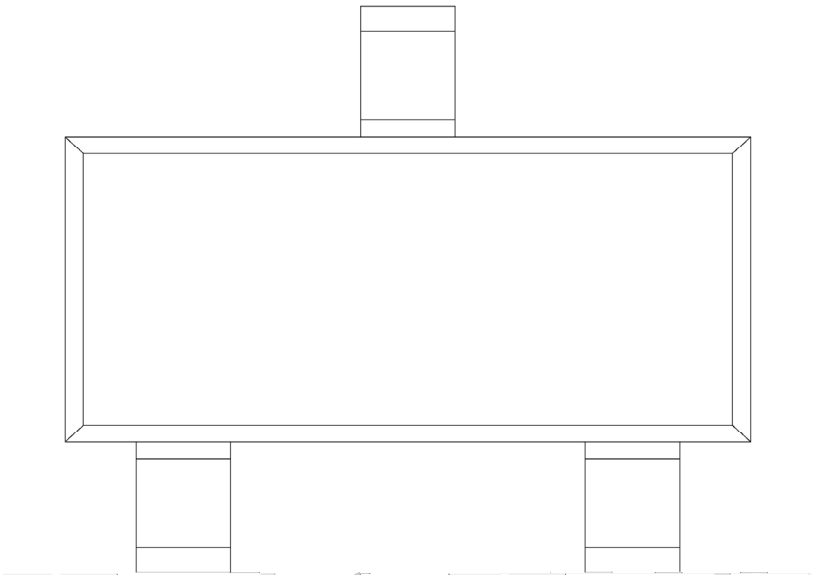
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	V_{CB}=20V I_E=0			0.1	μA
Collector-Base Breakdown Voltage	V_{CBO} 2SD602 2SD602A	I_C=10				

/ Electrical Characteristic Curve

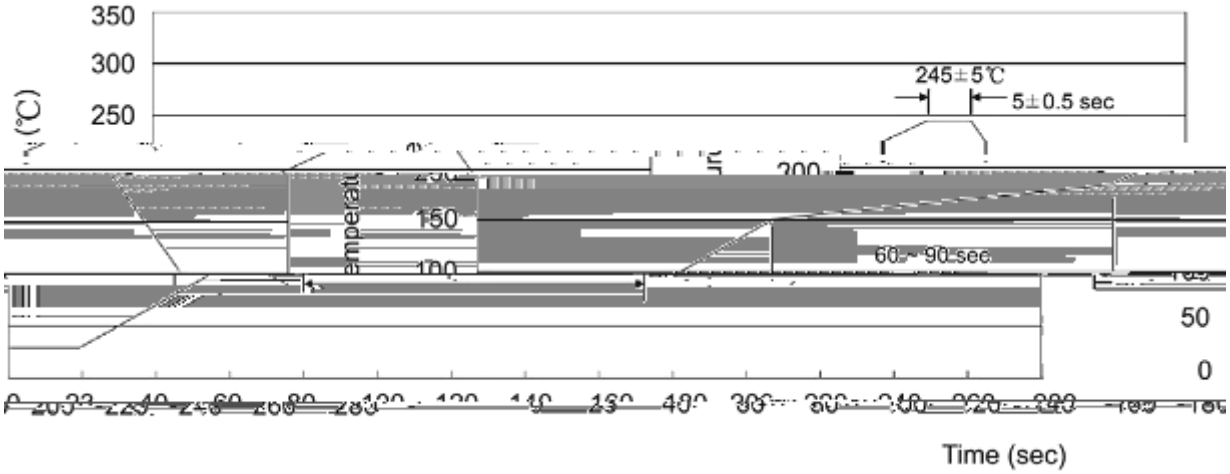


/ Package Dimensions





( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



				Note:	
1	25	150	60 90sec;	1.Preheating:25~150	, Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5	, Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ρ ×8	180×120×180	390×385×205

/ Notices